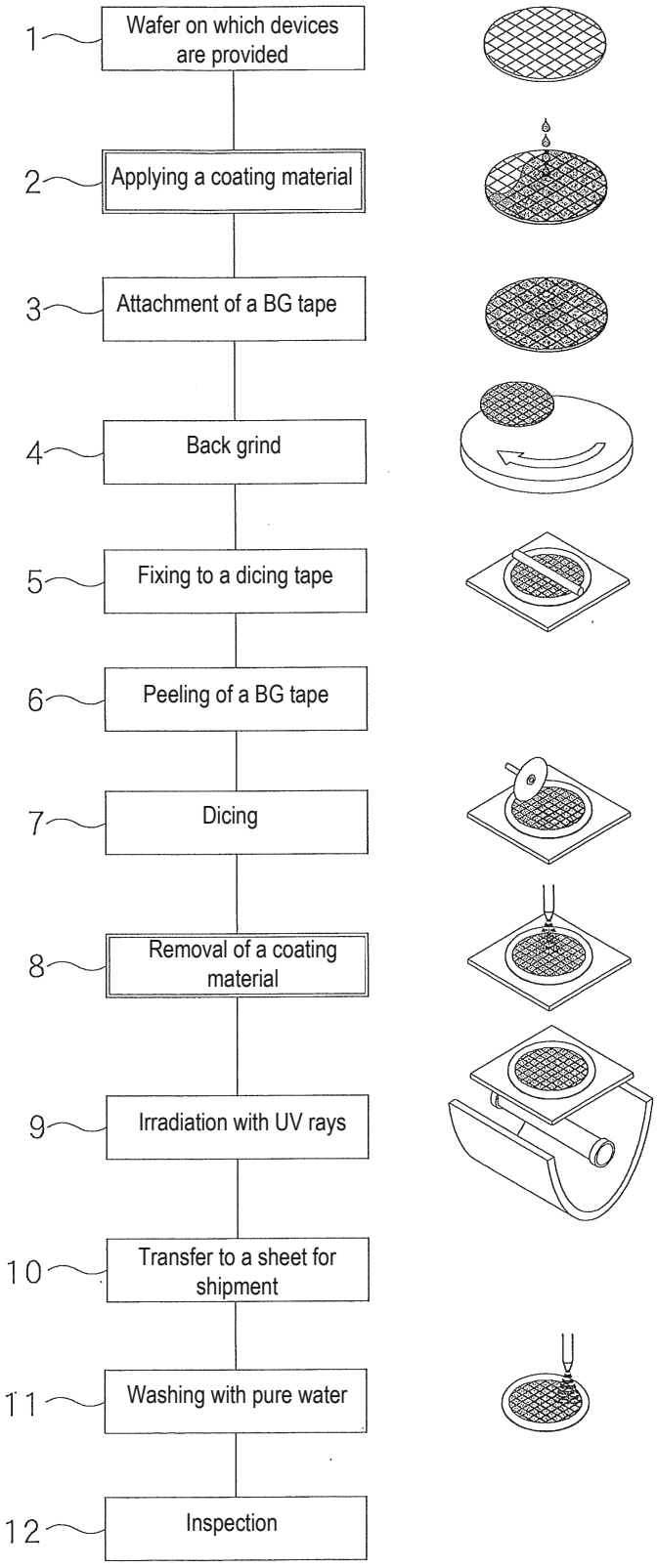
Fig. 1


1
Wafer on which devices are provided
2
Applying a coating material
3
Attachment of a BG tape
4
Back grind
5
Fixing to a dicing tape
6
Peeling of a BG tape
7
Dicing
8
Removal of a coating material
9
Irradiation with UV rays
10
Transfer to a sheet for shipment
11
Washing with pure water
12
Inspection